

8x930Ax UNIVERSAL SERIAL BUS MICROCONTROLLER

- **Complete Universal Serial Bus Specification 1.0 Compatibility**
 - Supports Isochronous and Non-isochronous Data
 - Bidirectional Half-duplex Link
- **On-chip USB Transceiver**
- **Serial Bus Interface Engine (SIE)**
 - Packet Decoding/Generation
 - CRC Generation and Checking
 - NRZI Encoding/Decoding and Bit-stuffing
- **USB Reset Interrupt**
- **Four Transmit FIFOs**
 - Three 16-byte FIFOs
 - One Configurable FIFO (up to 1 Kbyte)
- **Four Receive FIFOs**
 - Three 16-byte FIFOs
 - One Configurable FIFO (up to 1 Kbyte)
- **Automatic Transmit/Receive FIFO Management**
- **Suspend/Resume Operation**
- **Three New USB Interrupt Vectors**
 - USB Function Interrupt
 - Start of Frame
 - Suspend/Resume
- **Phase-locked Loop**
 - 12 Mbps or 1.5 Mbps Data Rate
- **Low Clock Mode**
- **User-selectable Configurations**
 - External Wait State
 - Address Range
 - Page Mode
- **Real-time Wait Function**
- **256-Kbyte External Code/Data Memory Space**
- **On-chip ROM Options**
 - 0, 8, or 16 Kbytes
- **1 Kbyte On-chip Data RAM**
- **Four Input/Output Ports**
 - 1 Open-drain port
 - 3 Quasi-bidirectional Ports
- **Programmable Counter Array (PCA)**
 - 5 Capture/Compare Modules
- **Serial I/O Port (UART)**
- **Hardware Watchdog Timer**
- **Three Flexible 16-bit Timer/Counters**
- **Power-saving Idle and Powerdown Modes**
- **Register-based MCS[®] 251 Architecture**
 - 40-byte Register File
 - Registers Accessible as Bytes, Words, or Doublewords
- **Code Compatible with MCS 51 and MCS 251 Microcontrollers**
- **6 or 12 MHz Crystal Operation**

The 8x930Ax USB microcontroller is based on an 8xC251Sx microcontroller core. It consists of standard 8xC251Sx peripherals plus an added USB function. The 8x930Ax uses the standard instruction set of the MCS 251 architecture, which is binary code compatible with the MCS 51 architecture. The USB function integrates the USB transceiver, serial bus interface engine (SIE), function interface unit (FIU) and transmit/receive FIFOs. The USB function also supports full-speed/low-speed data rates, suspend/resume modes, isochronous/non-isochronous transfers, and is fully compliant with the USB rev 1.0 specification.

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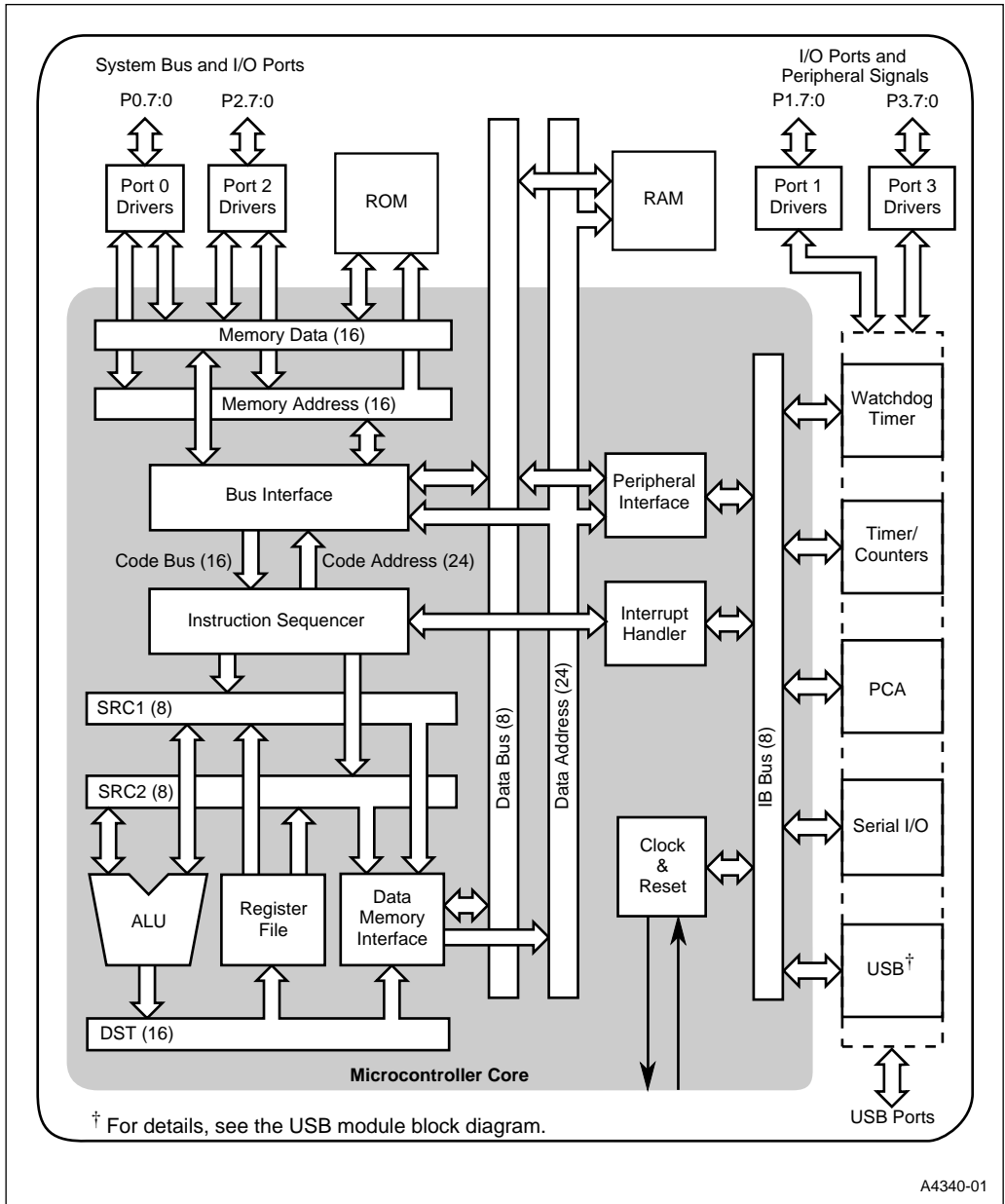
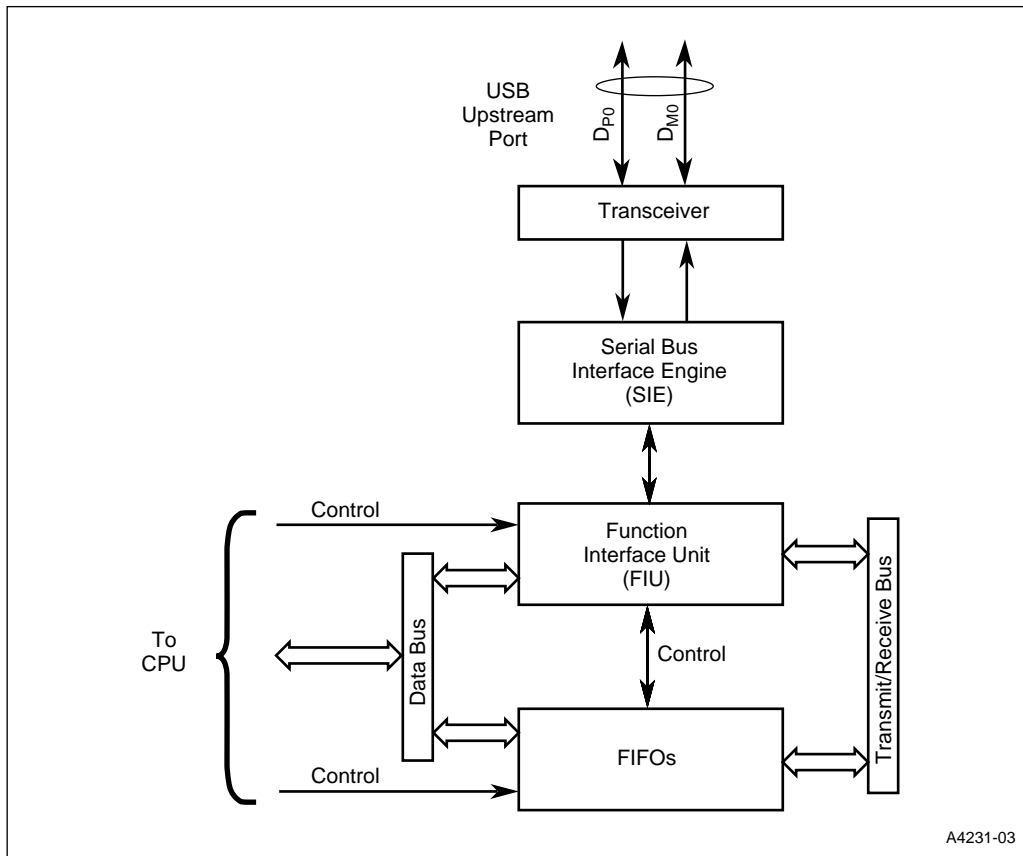


Figure 1. 8x930Ax Internal Block Diagram



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Figure 2. USB Module Block Diagram

1.0 NOMENCLATURE OVERVIEW

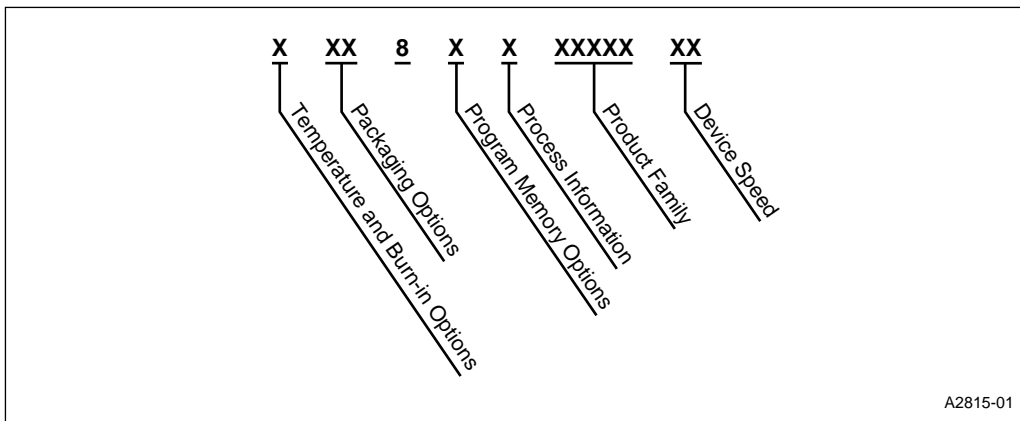


Figure 3. Product Nomenclature

Table 1. Description of Product Nomenclature

| Parameter | Options | Description |
|---------------------------------|---------|--|
| Temperature and Burn-in | no mark | Commercial operating temperature range (0°C to 70°C) with Intel standard burn-in. |
| Packaging Options | N | Plastic Leaded Chip Carrier (PLCC) |
| Program Memory Options | 0 | Without ROM |
| | 3 | With ROM |
| Process and Voltage Information | no mark | CHMOS |
| Product Family | 930 | Advanced 8-bit microcontroller architecture with on-chip Universal Serial Bus (USB) function peripherals |
| Device Speed | no mark | 6 or 12 MHz crystal |

Table 2. Proliferation Options

| Product Name | ROM Size | RAM Size |
|--------------|-----------|----------|
| 80930AD | 0 | 1 Kbyte |
| 83930AD | 8 Kbytes | 1 Kbyte |
| 83930AE | 16 Kbytes | 1 Kbyte |

2.0 PINOUT

Figure 4 illustrates the 8x930Ax PLCC package. Table 3 lists the pin assignments by pin number,

and Table 4 lists the pin assignments by functional categories. Table 5 describes the signals.

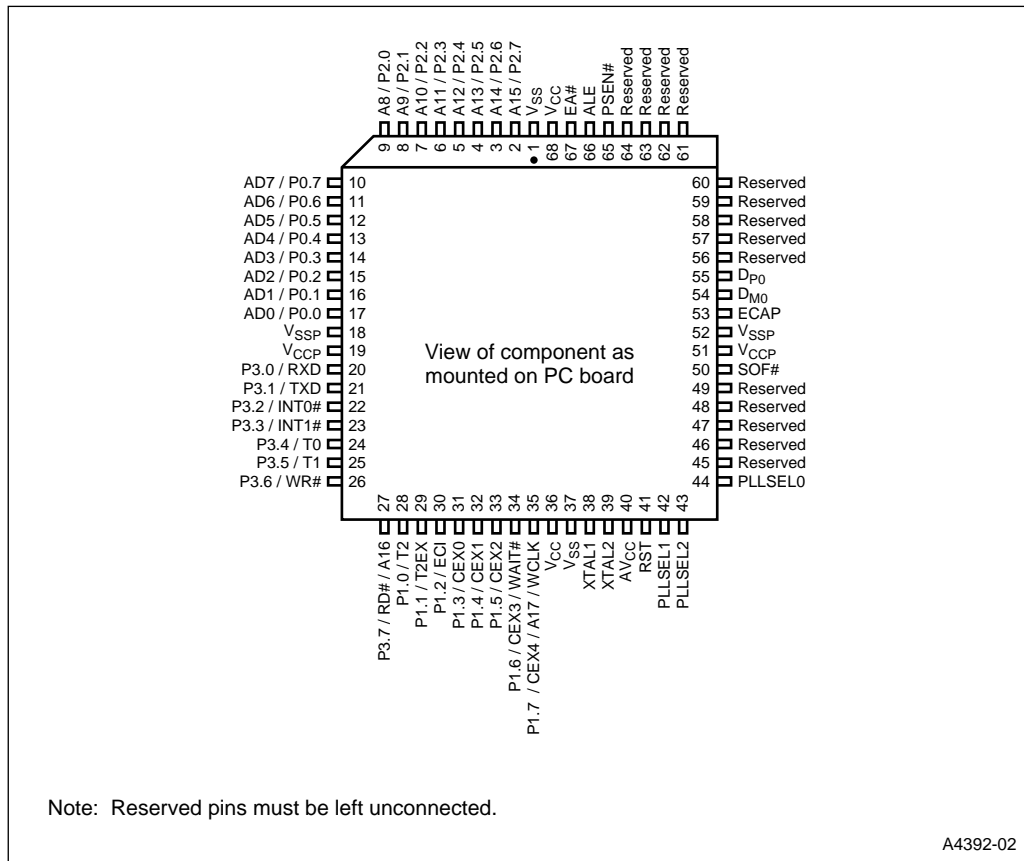


Figure 4. 8x930Ax 68-pin PLCC Package

Table 3. 68-pin PLCC Pin Assignment

| Pin | Name | Pin | Name | Pin | Name |
|-----|------------------|-----|--------------------|-----|------------------|
| 1 | V _{SS} | 24 | P3.4/T0 | 47 | Reserved |
| 2 | A15/P2.7 | 25 | P3.5/T1 | 48 | Reserved |
| 3 | A14/P2.6 | 26 | P3.6/WR# | 49 | Reserved |
| 4 | A13/P2.5 | 27 | P3.7/RD#/A16 | 50 | SOF# |
| 5 | A12/P2.4 | 28 | P1.0/T2 | 51 | V _{CCP} |
| 6 | A11/P2.3 | 29 | P1.1/T2EX | 52 | V _{SSP} |
| 7 | A10/P2.2 | 30 | P1.2/ECI | 53 | ECAP |
| 8 | A9/P2.1 | 31 | P1.3/CEX0 | 54 | D _{M0} |
| 9 | A8/P2.0 | 32 | P1.4/CEX1 | 55 | D _{P0} |
| 10 | AD7/P0.7 | 33 | P1.5/CEX2 | 56 | Reserved |
| 11 | AD6/P0.6 | 34 | P1.6/CEX3/WAIT# | 57 | Reserved |
| 12 | AD5/P0.5 | 35 | P1.7/CEX4/A17/WCLK | 58 | Reserved |
| 13 | AD4/P0.4 | 36 | V _{CC} | 59 | Reserved |
| 14 | AD3/P0.3 | 37 | V _{SS} | 60 | Reserved |
| 15 | AD2/P0.2 | 38 | XTAL1 | 61 | Reserved |
| 16 | AD1/P0.1 | 39 | XTAL2 | 62 | Reserved |
| 17 | AD0/P0.0 | 40 | AV _{CC} | 63 | Reserved |
| 18 | V _{SSP} | 41 | RST | 64 | Reserved |
| 19 | V _{CCP} | 42 | PLLSEL1 | 65 | PSEN# |
| 20 | P3.0/RXD | 43 | PLLSEL2 | 66 | ALE |
| 21 | P3.1/TXD | 44 | PLLSEL0 | 67 | EA# |
| 22 | P3.2/INT0# | 45 | Reserved | 68 | V _{CC} |
| 23 | P3.3/INT1# | 46 | Reserved | | |

Table 4. 68-pin PLCC Signal Assignments Arranged by Functional Category

| Address & Data | |
|--------------------|-----|
| Name | Pin |
| AD0/P0.0 | 17 |
| AD1/P0.1 | 16 |
| AD2/P0.2 | 15 |
| AD3/P0.3 | 14 |
| AD4/P0.4 | 13 |
| AD5/P0.5 | 12 |
| AD6/P0.6 | 11 |
| AD7/P0.7 | 10 |
| A8/P2.0 | 9 |
| A9/P2.1 | 8 |
| A10/P2.2 | 7 |
| A11/P2.3 | 6 |
| A12/P2.4 | 5 |
| A13/P2.5 | 4 |
| A14/P2.6 | 3 |
| A15/P2.7 | 2 |
| P3.7/RD#/A16 | 27 |
| P1.7/CEX4/A17/WCLK | 35 |

| Input/Output | |
|--------------------|-----|
| Name | Pin |
| P1.0/T2 | 28 |
| P1.1/T2EX | 29 |
| P1.2/ECI | 30 |
| P1.3/CEX0 | 31 |
| P1.4/CEX1 | 32 |
| P1.5/CEX2 | 33 |
| P1.6/CEX3/WAIT# | 34 |
| P1.7/CEX4/A17/WCLK | 35 |
| P3.0/RXD | 20 |
| P3.1/TXD | 21 |
| P3.4/T0 | 24 |
| P3.5/T1 | 25 |

| Bus Control & Status | |
|----------------------|-----|
| Name | Pin |
| P3.6/WR# | 26 |
| P3.7/RD#/A16 | 27 |
| ALE | 66 |
| PSEN# | 65 |

| Power & Ground | |
|------------------|--------|
| Name | Pin |
| V _{CC} | 36, 68 |
| V _{CCP} | 19, 51 |
| AV _{CC} | 40 |
| EA# | 67 |
| V _{SS} | 1, 37 |
| V _{SSP} | 18, 52 |

| USB | |
|-----------------|-----|
| Name | Pin |
| PLLSEL0 | 44 |
| PLLSEL1 | 42 |
| PLLSEL2 | 43 |
| SOF# | 50 |
| ECAP | 53 |
| D _{M0} | 54 |
| D _{P0} | 55 |

| Processor Control | |
|-------------------|-----|
| Name | Pin |
| P3.2/INT0# | 22 |
| P3.3/INT1# | 23 |
| EA# | 67 |
| RST | 41 |
| XTAL1 | 38 |
| XTAL2 | 39 |

3.0 SIGNALS

Table 5. Signal Descriptions

| Signal Name | Type | Description | Alternate Function |
|------------------------|------|---|---------------------------------------|
| A17 | O | 18th Address Bit (A17). Output to memory as 18th external address bit (A17) in extended bus applications, depending on the values of bits RD0 and RD1 in configuration byte UCONFIG0. See also RD#, PSEN#. | P1.7/CEX4/WCLK |
| A16 | O | Address Line 16. See RD#. | RD# |
| A15:8 [†] | O | Address Lines. Upper address lines for the external bus. | P2.7:0 |
| AD7:0 [†] | I/O | Address/Data Lines. Multiplexed lower address lines and data lines for external memory. | P0.7:0 |
| ALE | O | Address Latch Enable (ALE). ALE signals the start of an external bus cycle and indicates that valid address information is available on lines A15:8 and AD7:0. An external latch can use ALE to demultiplex the address from the address/data bus. | PROG# |
| AV _{CC} | PWR | Analog V_{CC}. A separate V _{CC} input for the phase-locked loop circuitry. | |
| CEX2:0 CEX3 CEX4 | I/O | Programmable Counter Array (PCA) Input/Output Pins. These are input signals for the PCA capture mode and output signals for the PCA compare mode and PCA PWM mode. | P1.5:3 P1.6/WAIT# P1.7/A17/WCLK |
| D _{M0} | I/O | Data Minus. USB minus data line interface. | — |
| D _{P0} | I/O | Data Plus. USB plus data line interface. | — |
| EA# | I | External Access. Directs program memory accesses to on-chip or off-chip code memory. For EA# strapped to ground, all program memory accesses are off-chip. For EA# strapped to V _{CC} , program accesses on-chip ROM if the address is within the range of the on-chip ROM; otherwise, the access is off-chip. The value of EA# is latched at reset. For devices without on-chip ROM, EA# must be strapped to ground. | |
| ECAP | I | External Capacitor. Must be connected to a 1 μF capacitor (or larger) to ensure proper operation of the differential line driver. The other lead of the capacitor must be connected to V _{SS} . | |
| ECI | I | PCA External Clock Input. External clock input to the 16-bit PCA timer. | P1.2 |
| INT1:0# | I | External Interrupts 0 and 1. These inputs set bits IE1:0 in the TCON register. If bits IT1:0 in the TCON register are set, bits IE1:0 are set by a falling edge on INT1#/INT0#. If bits INT1:0 are clear, bits IE1:0 are set by a low level on INT1:0#. | P3.3:2 |
| P0.7:0 | I/O | Port 0. This is an 8-bit, open-drain, bidirectional I/O port. | AD7:0 |

[†] The descriptions of A15:8/P2.7:0 and AD7:0/P0.7:0 are for the nonpage-mode chip configuration. If the chip is configured for page-mode operation, port 0 carries the lower address bits (A7:0), and port 2 carries the upper address bits (A15:8) and the data (D7:0).

Table 5. Signal Descriptions (Continued)

| Signal Name | Type | Description | Alternate Function |
|--|------|--|--|
| P1.0 P1.1 P1.2 P1.5:3 P1.6 P1.7 | I/O | Port 1. This is an 8-bit, bidirectional I/O port with internal pullups. | T2 T2EX ECI CEX2:0 CEX3/WAIT# CEX4/A17/WCLK |
| P2.7:0 | I/O | Port 2. This is an 8-bit, bidirectional I/O port with internal pullups. | A15:8 |
| P3.0 P3.1 P3.3:2 P3.5:4 P3.6 P3.7 | I/O | Port 3. This is an 8-bit, bidirectional I/O port with internal pullups. | RXD TXD INT1:0# T1:0 WR# RD#/A16 |
| PLLSEL2:0 | I | Phase-locked Loop Select. Three-bit code selects USB data rate (see Table 8 on page 12). | — |
| PSEN# | O | Program Store Enable. Read signal output. This output is asserted for a memory address range that depends on bits RD0 and RD1 in configuration byte UCONFIG0 (see RD#). | — |
| RD# | O | Read or 17th Address Bit (A16). Read signal output to external data memory or 17th external address bit (A16), depending on the values of bits RD0 and RD1 in configuration byte UCONFIG0 (See PSEN#). | P3.7/A16 |
| RST | I | Reset. Reset input to the chip. Holding this pin high for 64 oscillator periods while the oscillator is running resets the device. The port pins are driven to their reset conditions when a voltage greater than V_{IH1} is applied, whether or not the oscillator is running. This pin has an internal pulldown resistor which allows the device to be reset by connecting a capacitor between this pin and V_{CC} . Asserting RST when the chip is in idle mode or powerdown mode returns the chip to normal operation. | — |
| RXD | I/O | Receive Serial Data. RXD sends and receives data in serial I/O mode 0 and receives data in serial I/O modes 1, 2, and 3. | P3.0 |
| SOF# | O | Start of Frame. Start of Frame pulse. Active low, asserted for 8 states (see Table 8 on page 12 for state versus XTAL clock) when Frame Timer is locked to USB frame timing and SOF token or artificial SOF is detected. | — |
| T1:0 | I | Timer 1:0 External Clock Inputs. When timer 1:0 operates as a counter, a falling edge on the T1:0 pin increments the count. | P3.5:4 |
| T2 | I/O | Timer 2 Clock Input/Output. For the timer 2 capture mode, this signal is the external clock input. For the clock-out mode, it is the timer 2 clock output. | P1.0 |

† The descriptions of A15:8/P2.7:0 and AD7:0/P0.7:0 are for the nonpage-mode chip configuration. If the chip is configured for page-mode operation, port 0 carries the lower address bits (A7:0), and port 2 carries the upper address bits (A15:8) and the data (D7:0).

Table 5. Signal Descriptions (Continued)

| Signal Name | Type | Description | Alternate Function |
|------------------|------|--|--------------------|
| T2EX | I | Timer 2 External Input. In timer 2 capture mode, a falling edge initiates a capture of the timer 2 registers. In auto-reload mode, a falling edge causes the timer 2 registers to be reloaded. In the up-down counter mode, this signal determines the count direction: 1 = up, 0 = down. | P1.1 |
| TXD | O | Transmit Serial Data. TXD outputs the shift clock in serial I/O mode 0 and transmits serial data in serial I/O modes 1, 2, and 3. | P3.1 |
| V _{CC} | PWR | Supply Voltage. Connect this pin to the +5V supply voltage. | — |
| V _{CCP} | PWR | Supply Voltage for I/O buffers. Connect this pin to the +5V supply voltage. | — |
| V _{SS} | GND | Circuit Ground. Connect this pin to ground. | — |
| V _{SSP} | GND | Circuit Ground for I/O buffers. Connect this pin to ground. | — |
| WAIT# | I | Real-time Wait State Input. The real-time WAIT# input is enabled by writing a logical '1' to the WCON.0 (RTWE) bit at S:A7H. During bus cycles, the external memory system can signal 'system ready' to the microcontroller in real time by controlling the WAIT# input signal on the port 1.6 input. | P1.6/CEX3 |
| WCLK | O | Wait Clock Output. The real-time WCLK output is driven at port 1.7 (WCLK) by writing a logical '1' to the WCON.1 (RTWCE) bit at S:A7H. When enabled, the WCLK output produces a square wave signal with a period of T _{CLK} . | P1.7/CEX4/A17 |
| WR# | O | Write. Write signal output to external memory. | P3.6 |
| XTAL1 | I | Input to the On-chip, Inverting, Oscillator Amplifier. To use the internal oscillator, a crystal/resonator circuit is connected to this pin. If an external oscillator is used, its output is connected to this pin. XTAL1 is the clock source for internal timing. | — |
| XTAL2 | O | Output of the On-chip, Inverting, Oscillator Amplifier. To use the internal oscillator, a crystal/resonator circuit is connected to this pin. If an external oscillator is used, leave XTAL2 unconnected. | — |

† The descriptions of A15:8/P2.7:0 and AD7:0/P0.7:0 are for the nonpage-mode chip configuration. If the chip is configured for page-mode operation, port 0 carries the lower address bits (A7:0), and port 2 carries the upper address bits (A15:8) and the data (D7:0).

Table 6. Memory Signal Selections (RD1:0)

| RD1:0 † | A17/P1.7 /CEX4/WCLK | A16/P3.7/RD# | PSEN# | WR# | Features |
|------------|------------------------|---------------------------------------|-----------------------------------|---|---|
| 0 0 | A17 | A16 | Asserted for all addresses | Asserted for writes to all memory locations | 256-Kbyte external memory |
| 0 1 | P1.7/CEX4/WCLK | A16 | Asserted for all addresses | Asserted for writes to all memory locations | 128-Kbyte external memory |
| 1 0 | P1.7/CEX4/WCLK | P3.7 only | Asserted for all addresses | Asserted for writes to all memory locations | 64-Kbyte external memory One additional port pin |
| 1 1 | P1.7/CEX4/WCLK | RD# Asserted for addresses ≤ 7F:FFFFH | Asserted for addresses ≥ 80:0000H | Asserted for all compatible MCS 51 memory locations | Compatible with MCS 51 microcontrollers |

† RD1:0 are bits 3:2 of configuration byte UCONFIG0. Refer to figure 4-3 on page 4-5 in the *8x930Ax Universal Serial Bus Microcontroller User's Manual*.

4.0 ADDRESS MAP

Table 7. 8x930Ax Address Map

| Internal Address | Description | Notes |
|----------------------|---|---------|
| FF:FFFFH FF:0000H | External Memory: The last eight bytes of the external address range FF:XFF8H–FF:XFFFH contain configuration byte information. | 1, 2, 3 |
| FE:FFFFH FE:0000H | External Memory | 2 |
| FD:FFFFH 02:0000H | Reserved Addresses | 4 |
| 01:FFFFH 01:0000H | External Memory | 2 |
| 00:FFFFH 00:0420H | External Memory | 5 |
| 00:041FH 00:0080H | On-chip RAM | 5 |
| 00:007FH 00:0020H | On-chip RAM | 6 |
| 00:001FH 00:0000H | Storage for R0–R7 of Register File | 7, 8 |

NOTES:

- Eighteen address lines are bonded out (A15:0, A16:0, or A17:0 selected during chip configuration).
- Data in this area is accessible by indirect addressing only.
- Eight addresses at the top of all external memory maps are reserved for current and future device configuration byte information.
- This reserved area returns unspecified values and writes no data.
- Data is accessible by direct and indirect addressing.
- Data is accessible by direct, indirect, and bit addressing.
- The special function registers (SFRs) and the register file have separate internal address spaces.
- Data is accessible by direct, indirect, and register addressing.

5.0 ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

| | |
|---------------------------------------|------------------|
| Ambient Temperature Under Bias..... | -40°C to +85°C |
| Storage Temperature | -65°C to +150°C |
| Voltage on Any Pins to V_{SS} | -0.5 V to +6.5 V |
| I_{OL} per I/O Pin | 15 mA |
| Power Dissipation | 1.5 W |

NOTICE: This document contains information on products in the sampling and initial production phases of development. The specifications are subject to change without notice. Verify with your local Intel sales office that you have the latest datasheet before finalizing a design.

OPERATING CONDITIONS[†]

| | |
|---|------------------|
| T_A (Ambient Temperature Under Bias): | |
| Commercial | -0°C to +70°C |
| V_{CC}/V_{CCP} (Digital Supply Voltage) | 4.00 V to 5.25 V |
| V_{SS} / V_{SSP} | 0 V |
| AV_{CC} (Analog Supply Voltage) | 4.00 V to 5.25 V |
| F_{OSC} | 6 MHz or 12 MHz |

[†] **WARNING:** *Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.*

NOTE: Maximum power dissipation is based on package heat-transfer limitations, not device power consumption.

5.1 Operating Frequencies

Table 8. Frequency Selection and Operating Frequency

| PLLSEL2 Pin 43 | PLLSEL1 Pin 42 | PLLSEL0 Pin 44 | USB Rate (Low Speed or Full Speed) | 8x930Ax Internal Frequency for CPU and Peripherals (F_{CLK}) (5) | XTAL1 External Frequency (F_{OSC}) | Number of XTAL1 Clocks (T_{OSC}) in One StateTime (4) | Comments |
|-------------------|-------------------|-------------------|--|---|---|---|----------|
| 0 | 0 | 1 | 1.5 Mbps (LS) | 3 MHz | 6 MHz | $2 T_{OSC}/state$ | PLL Off |
| 1 | 0 | 0 | 1.5 Mbps (LS) | 6 MHz (3) | 12 MHz | $2 T_{OSC}/state$ | PLL Off |
| 1 | 1 | 0 | 12 Mbps (FS) | 12 MHz (3) | 12 MHz | $1 T_{OSC}/state$ | PLL On |

NOTES:

- Other PLLSELx combinations are not valid.
- The sampling rate is 4X the USB rate.
- The 8x930Ax CPU and peripherals frequency is 3 MHz (low clock mode) until firmware disables the low clock mode.
- The number of XTAL clocks in one state depends on the PLLSELx selections. When the CPU is operating at low clock mode (3 MHz), there are four T_{OSC} per state for the PLLSEL2:1:0 = 100 and 110.
- The AC timing specification (Table 11) defines the following symbol: CPU frequency = $F_{CLK} = 1/T_{CLK}$.

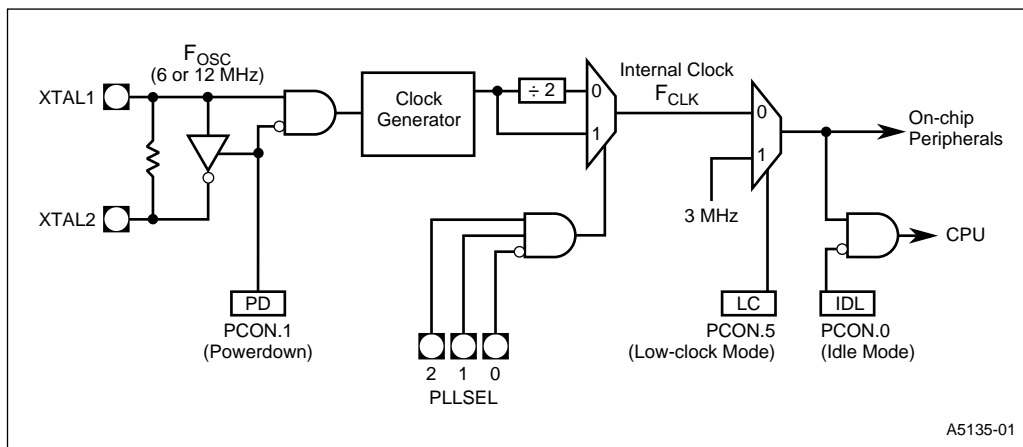


Figure 5. Clock Circuit

A5135-01

5.2 DC Characteristics

Table 9. DC Characteristics at Operating Conditions

| Symbol | Parameter | Min | Typical (1) | Max | Units | Test Conditions |
|-----------|--|--|-------------|--------------------|---------------|---|
| V_{IL} | Input Low Voltage (Except EA#) | -0.5 | | $0.2 V_{CC} - 0.1$ | V | |
| V_{IL1} | Input Low Voltage (EA#) | 0 | | $0.2 V_{CC} - 0.3$ | V | |
| V_{IH} | Input High Voltage (Except XTAL1, RST) | $0.2 V_{CC} + 0.9$ | | $V_{CC} + 0.5$ | V | |
| V_{IH1} | Input High Voltage (XTAL1, RST) | $0.7 V_{CC}$ | | $V_{CC} + 0.5$ | V | |
| V_{OL} | Output Low Voltage (Port 1, 2, 3) | | | 0.3 0.45 1.0 | V | $I_{OL} = 100 \mu\text{A}$ (2, 3) $I_{OL} = 1.6 \text{ mA}$ $I_{OL} = 3.5 \text{ mA}$ |
| V_{OL1} | Output Low Voltage (Port 0, ALE, PSEN#, SOF#) | | | 0.3 0.45 1.0 | V | $I_{OL} = 200 \mu\text{A}$ (2, 3) $I_{OL} = 3.2 \text{ mA}$ $I_{OL} = 7.0 \text{ mA}$ |
| V_{OH} | Output High Voltage (Port 1, 2, 3, ALE, PSEN#, SOF#) | $V_{CC} - 0.3$ $V_{CC} - 0.7$ $V_{CC} - 1.5$ | | | V | $I_{OH} = -10 \mu\text{A}$ (4) $I_{OH} = -30 \mu\text{A}$ $I_{OH} = -60 \mu\text{A}$ |
| V_{OH1} | Output High Voltage (Port 0 in External Address) | $V_{CC} - 0.3$ $V_{CC} - 0.7$ $V_{CC} - 1.5$ | | | V | $I_{OH} = -200 \mu\text{A}$ (4) $I_{OH} = -3.2 \text{ mA}$ $I_{OH} = -7.0 \text{ mA}$ |
| I_{IL} | Logical 0 Input Current (Port 1,2,3) | | | -150 | μA | $V_{IN} = 0.45 \text{ V}$ |
| I_{LI} | Input Leakage Current (Port 0) | | | ± 10 | μA | $0.45 < V_{IN} < V_{CC}$ |

NOTE:

- Typical values are obtained using $V_{CC} = 5.0\text{V}$, $T_A = 25^\circ\text{C}$ and are not guaranteed.
- Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
 Maximum I_{OH} per port pin: 10 mA
 Maximum I_{OL} per 8-bit port:
 Port 0: 26 mA Ports 1-3: 15 mA
 Maximum Total I_{OL} for all output pins: 71 mA
 If I_{OL} exceeds the test conditions, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
- Capacitive loading on Ports 0 and 2 may cause spurious noise pulses above 0.4 V on the low-level outputs of ALE and Ports 1, 2 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins change from 1 to 0. In applications where capacitive loading exceeds 100pF, the noise pulses on these signals may exceed 0.8 V. It may be desirable to qualify ALE or other signals with a Schmitt Trigger or CMOS-level input logic.
- Capacitive loading on Ports 0 and 2 cause the V_{OH} on ALE and PSEN to drop below the V_{CC} specification when the address lines are stabilizing.
- The abbreviations "LS" and "FS" indicate "Low Speed" and "Full Speed," respectively.

Table 9. DC Characteristics at Operating Conditions (Continued)

| Symbol | Parameter | Min | Typical (1) | Max | Units | Test Conditions |
|--------------|--|-----|-------------|-----------|------------------|---|
| I_{TL} | Logical 1-to-0 Transition Current (Port 1, 2,3) | | | -650 | μA | $V_{IN} = 2.0\text{ V}$ |
| R_{RST} | RST Pulldown Resistor | 40 | | 225 | $\text{K}\Omega$ | |
| C_{IO} | | | 10 | | pF | $F_{OSC} = 12\text{ MHz}$ $T_A = 25^\circ\text{C}$ |
| I_{PD} | Powerdown Current — Normal powerdown — USB suspend | | 25 145 | 50 175 | μA | |
| I_{DL} (5) | Idle Mode I_{CC} | | | 40 | mA | PLLSEL = 110 3MHz – FS (in low clock mode) |
| | | | | 100 | | PLLSEL = 110 12MHz – FS (not in low clock mode) |
| | | | | 30 | | PLLSEL = 001 3MHz – LS |
| | | | | 55 | | PLLSEL = 100 6 MHz – LS |

NOTE:

- Typical values are obtained using $V_{CC} = 5.0\text{V}$, $T_A = 25^\circ\text{C}$ and are not guaranteed.
- Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
Maximum I_{OH} per port pin: 10 mA
Maximum I_{OL} per 8-bit port:
Port 0: 26 mA Ports 1-3: 15 mA
Maximum Total I_{OL} for all output pins: 71 mA
If I_{OL} exceeds the test conditions, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
- Capacitive loading on Ports 0 and 2 may cause spurious noise pulses above 0.4 V on the low-level outputs of ALE and Ports 1, 2 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins change from 1 to 0. In applications where capacitive loading exceeds 100pF, the noise pulses on these signals may exceed 0.8 V. It may be desirable to qualify ALE or other signals with a Schmitt Trigger or CMOS-level input logic.
- Capacitive loading on Ports 0 and 2 cause the V_{OH} on ALE and PSEN to drop below the V_{CC} specification when the address lines are stabilizing.
- The abbreviations “LS” and “FS” indicate “Low Speed” and “Full Speed,” respectively.

Table 9. DC Characteristics at Operating Conditions (Continued)

| Symbol | Parameter | Min | Typical (1) | Max | Units | Test Conditions |
|--------------|-----------------|-----|-------------|-----|-------|--|
| I_{CC} (5) | Active I_{CC} | | | 60 | mA | PLLSEL = 110 3 MHz – FS (in low clock mode) |
| | | | | 150 | | PLLSEL = 110 12 MHz – FS (not in low clock mode) |
| | | | | 45 | | PLLSEL = 001 3 MHz – LS |
| | | | | 75 | | PLLSEL = 100 6 MHz – LS |

NOTE:

- Typical values are obtained using $V_{CC} = 5.0V$, $T_A = 25^\circ C$ and are not guaranteed.
- Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
 Maximum I_{OH} per port pin: 10 mA
 Maximum I_{OL} per 8-bit port:
 Port 0: 26 mA Ports 1-3: 15 mA
 Maximum Total I_{OL} for all output pins: 71 mA
 If I_{OL} exceeds the test conditions, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
- Capacitive loading on Ports 0 and 2 may cause spurious noise pulses above 0.4 V on the low-level outputs of ALE and Ports 1, 2 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins change from 1 to 0. In applications where capacitive loading exceeds 100pF, the noise pulses on these signals may exceed 0.8 V. It may be desirable to qualify ALE or other signals with a Schmitt Trigger or CMOS-level input logic.
- Capacitive loading on Ports 0 and 2 cause the V_{OH} on ALE and PSEN to drop below the V_{CC} specification when the address lines are stabilizing.
- The abbreviations “LS” and “FS” indicate “Low Speed” and “Full Speed,” respectively.

5.3 Definition of AC Symbols

Table 10. AC Timing Symbol Definitions

| Signals | | Conditions | |
|---------|-----------|------------|----------|
| A | Address | H | High |
| D | Data In | L | Low |
| L | ALE | V | Valid |
| Q | Data Out | X | Hold |
| R | RD#/PSEN# | Z | Floating |
| W | WR# | | |

5.4 AC Characteristics

Test Conditions: Capacitive load on all pins = 50 pF, Rise and Fall times = 10 ns, $F_{OSC} = 6$ MHz or 12 MHz

5.4.1 SYSTEM BUS AC CHARACTERISTICS

Table 11. AC Characteristics at Operating Conditions

| Symbol | Parameter | CPU Frequency @ 12 MHz (M, N = 0) | CPU Frequency (F_{CLK}) Variable | | Units |
|-----------------|---|---|--------------------------------------|-----------------------|--------------|
| | | | Min | Max | |
| T_{CLK} | 1/(CPU Frequency) | 83.33 (Typical) | | | ns (1, 2) |
| T_{LHLL} | ALE Pulse Width | 34.66 | $(0.5+M)T_{CLK} - 7$ | | ns (3) |
| T_{AVLL} | Address Valid to ALE Low | 26.66 | $(0.5+M)T_{CLK} - 17$ | | ns (3) |
| T_{LLAX} | Address Hold after ALE Low | 4 | 4 | | ns (4) |
| T_{RLRH} (5) | RD# or PSEN# Pulse Width | 73.33 | $(1+N)T_{CLK} - 10$ | | ns (6) |
| T_{WLWH} | WR# Pulse Width | 71.33 | $(1+N)T_{CLK} - 12$ | | ns (6) |
| T_{LLRL} (5) | ALE Low to RD# or PSEN# Low | 8 | 8 | | ns |
| T_{LHAX} | ALE High to Address Hold | 40.33 | $(1+M)T_{CLK} - 43$ | | ns (3) |
| T_{RLDV} (5) | RD# or PSEN# Low to Valid Data/Instruction In | 50.33 | | $(1+N)T_{CLK} - 33$ | ns (6) |
| T_{RHDX} (5) | Data/Instruction. Hold After RD# or PSEN# High | 0 | 0 | | ns |
| T_{RLAZ} (5) | RD# or PSEN# Low to Address Float | 0 | | 0 | ns |
| T_{RHDZ1} (5) | Instruct. Float After PSEN# High | 10 | | 10 | ns |
| T_{RHDZ2} (5) | Data Float After RD# or PSEN# High | 83.33 | | T_{CLK} | ns |
| T_{RHLH1} (5) | PSEN# High to ALE High (Instruction) | 10 | 10 | | ns |
| T_{RHLH2} (5) | RD# or PSEN# High to ALE High (Data) | 83.33 | T_{CLK} | | ns |
| T_{WHLH} | WR# High to ALE High | 88.33 | $T_{CLK} + 5$ | | ns |
| T_{AVDV1} | Address (P0) Valid to Valid Data/Instruction In | 106.66 | | $(2+M+N)T_{CLK} - 63$ | ns (3, 6) |

NOTES:

1. Refer to Table 8 on page 12 for CPU frequencies vs. XTAL1 frequencies.
2. XTAL1 frequency is $\pm 0.25\%$ for full speed and $\pm 1.5\%$ for low speed.
3. M= 0,1 is the extended ALE state.
4. At 50° C, $T_{LLAX} = 8$ ns
5. Specifications for PSEN# are identical to those for RD#.
6. N= 0,1,2,3 is the RD#/PSEN#/WR# wait state.

Table 11. AC Characteristics at Operating Conditions (Continued)

| Symbol | Parameter | CPU Frequency @ 12 MHz (M, N = 0) | CPU Frequency (F_{CLK}) Variable | | Units |
|----------------|---|---|--------------------------------------|-----------------------|--------------|
| | | | Min | Max | |
| T_{AVDV2} | Address (P2) Valid to Valid Data/Instruction In | 118.66 | | $(2+M+N)T_{CLK} - 48$ | ns (3, 6) |
| T_{AVDV3} | Address (P2) Valid to Valid Instruction In | 23.33 | | $(1+N)T_{CLK} - 60$ | ns (6) |
| T_{AVRL} (5) | Address Valid to RD# or PSEN# Low | 40.33 | $(1+M)T_{CLK} - 46$ | | ns (3) |
| T_{AVWL1} | Address (P0) Valid to WR# Low | 40.33 | $(1+M)T_{CLK} - 46$ | | ns (3) |
| T_{AVWL2} | Address (P2) Valid to WR# Low | 66.33 | $(1+M)T_{CLK} - 17$ | | ns (3) |
| T_{WHQX} | Data Hold after WR# High | 28.66 | $0.5 T_{CLK} - 13$ | | ns |
| T_{QVWH} | Data Valid to WR# High | 68.33 | $(1+N)T_{CLK} - 15$ | | ns (6) |
| T_{WHAX} | WR# High to Address Hold | 70.33 | $T_{CLK} - 13$ | | ns |

NOTES:

1. Refer to Table 8 on page 12 for CPU frequencies vs. XTAL1 frequencies.
2. XTAL1 frequency is $\pm 0.25\%$ for full speed and $\pm 1.5\%$ for low speed.
3. M= 0,1 is the extended ALE state.
4. At 50° C, $T_{LLAX} = 8$ ns
5. Specifications for PSEN# are identical to those for RD#.
6. N= 0,1,2,3 is the RD#/PSEN#/WR# wait state.

5.4.2 SYSTEM BUS TIMING DIAGRAMS, NONPAGE MODE

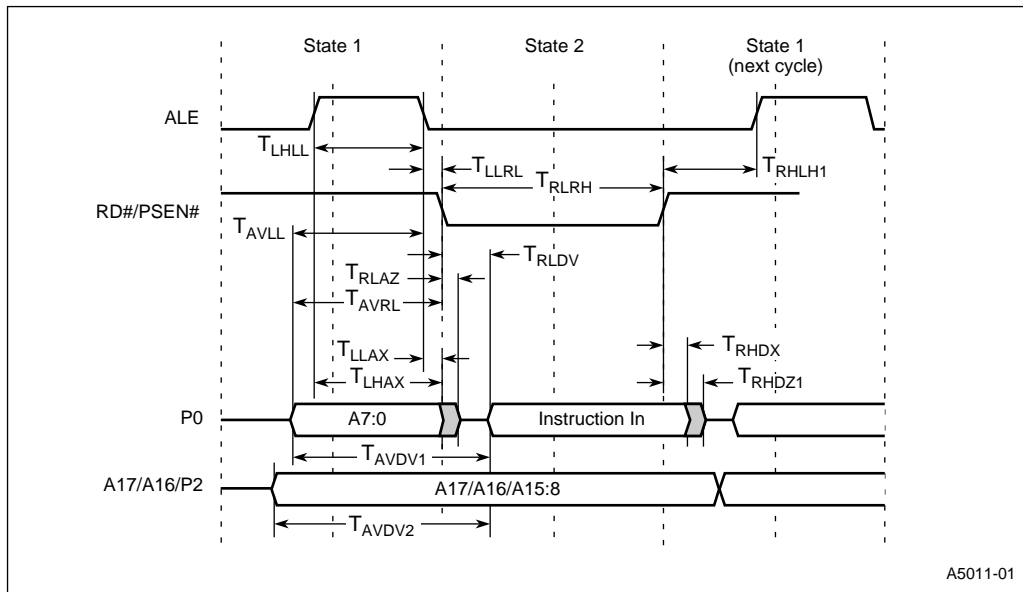
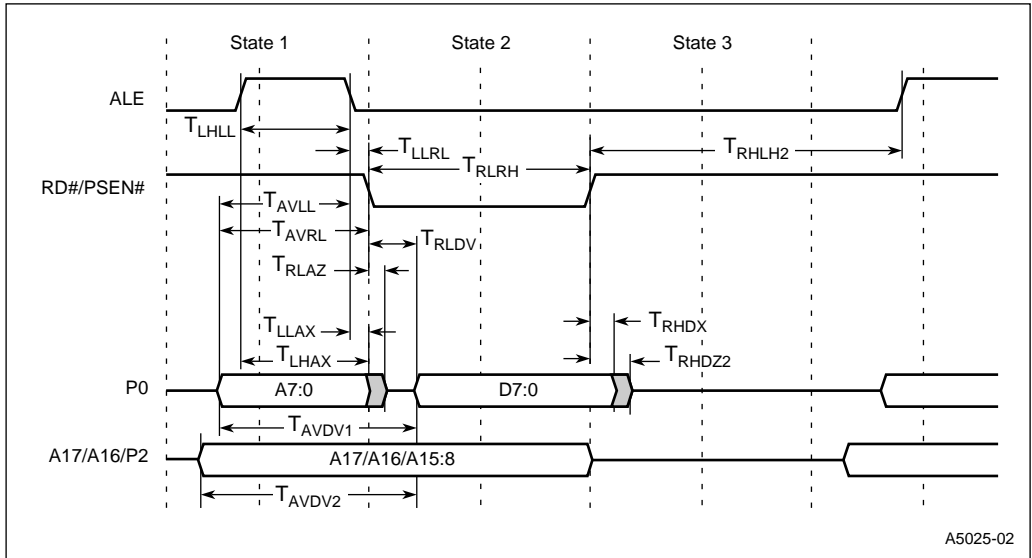
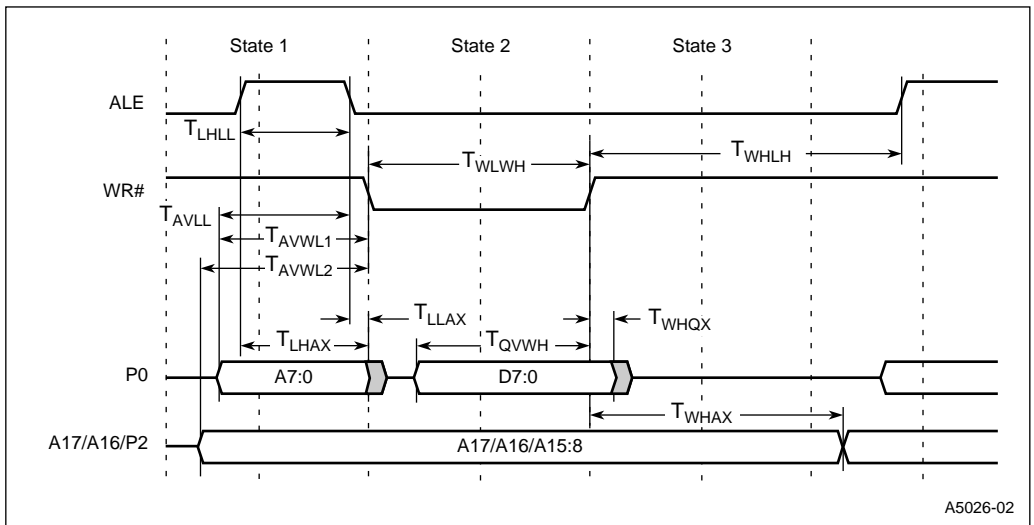


Figure 6. 8x930Ax Code Fetch, Nonpage Mode



A5025-02

Figure 7. 8x930Ax Data Read, Nonpage Mode



A5026-02

Figure 8. 8x930Ax Data Write, Nonpage Mode

5.4.3 SYSTEM BUS TIMING DIAGRAMS, PAGE MODE

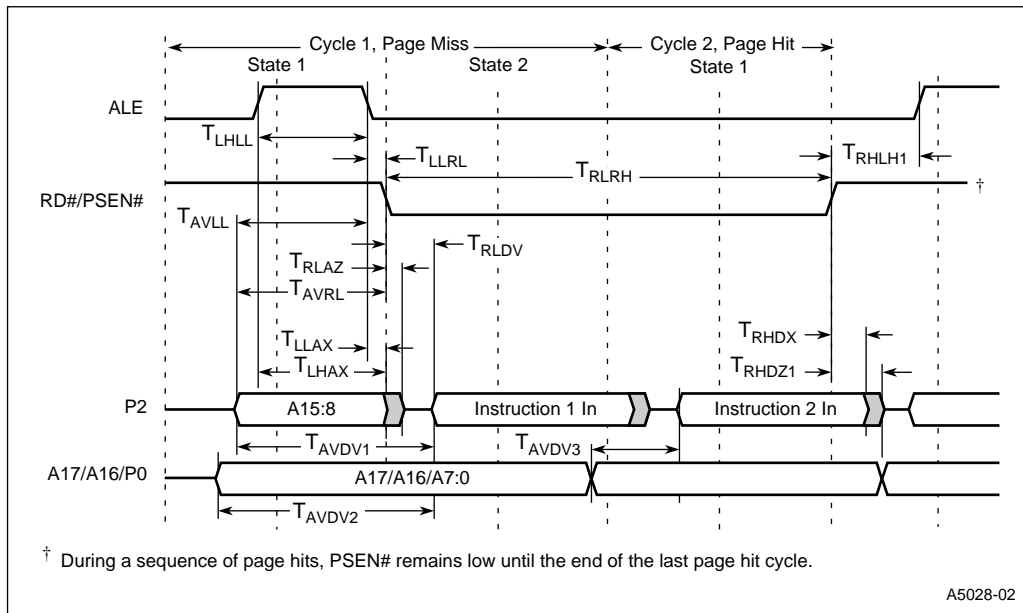


Figure 9. 8x930Ax Code Fetch, Page Mode

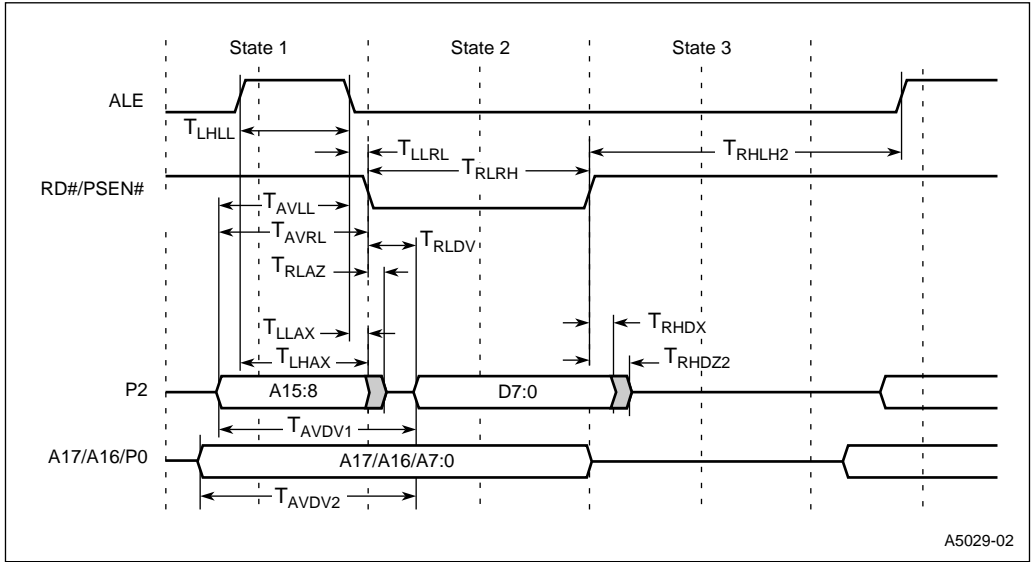


Figure 10. 8x930Ax Data Read, Page Mode

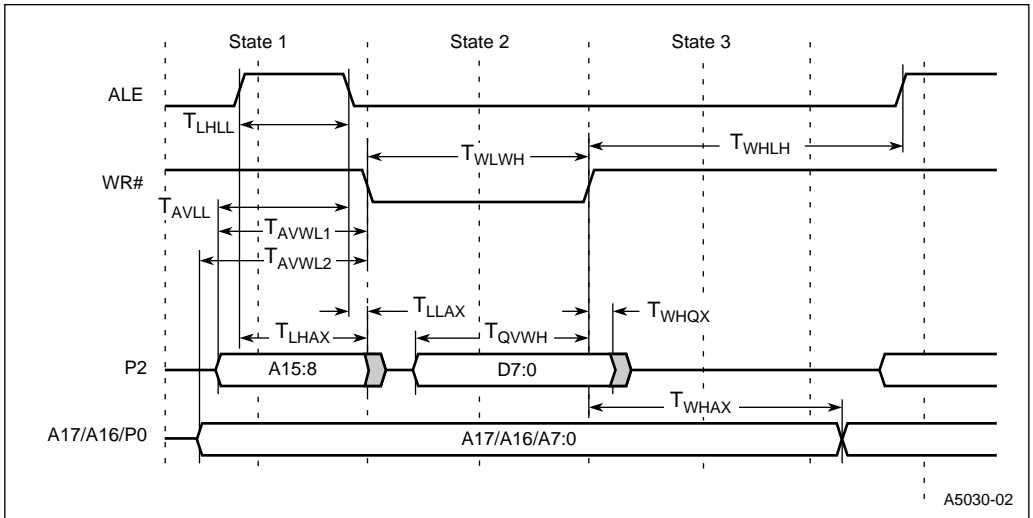


Figure 11. 8x930Ax Data write, Page Mode

5.4.4 DEFINITION OF REAL-TIME WAIT SYMBOLS

Table 12. Real-time Wait Timing Symbol Definitions

| Signals | | Conditions | |
|---------|-----------|------------|-------|
| A | Address | L | Low |
| D | Data | X | Hold |
| C | WCLK | V | Setup |
| Y | WAIT# | | |
| W | WR# | | |
| R | RD#/PSEN# | | |

5.4.5 REAL-TIME WAIT FUNCTION AC CHARACTERISTICS

Table 13. Real-time Wait AC Timing Specifications

| Symbol | Parameter | F _{CLK} Variable ^{(1) (2)} | | | Units |
|-------------------|----------------------------------|--|-----|------------------------------|-------|
| | | Min | Typ | Max | |
| T _{CLYV} | Wait Clock Low to Wait Setup | 0 | | 0.5 T _{CLK} - 13 | ns |
| T _{CLYX} | Wait Hold after Wait Clock Low | (W)T _{CLK} + 5 | | (0.5+W)T _{CLK} - 13 | ns |
| T _{RLYV} | PSEN# or RD# Low to Wait Setup | 0 | | 0.5 T _{CLK} - 13 | ns |
| T _{RLYX} | Wait Hold after PSEN# or RD# Low | (W)T _{CLK} + 5 | | (0.5+W)T _{CLK} - 13 | ns |
| T _{WLYV} | WR# Low to Wait Setup | 0 | | 0.5 T _{CLK} - 13 | ns |
| T _{WLYX} | Wait Hold after WR# Low | (W)T _{CLK} + 5 | | (0.5+W)T _{CLK} - 13 | ns |

NOTES:

1. W = 0, 1, 2, ... is the number of real-time wait states.
2. Real-time Wait function has a critical timing for instruction read. It is not advisable to use this feature for instruction read during page mode.

5.4.6 REAL-TIME WAIT FUNCTION TIMING DIAGRAMS

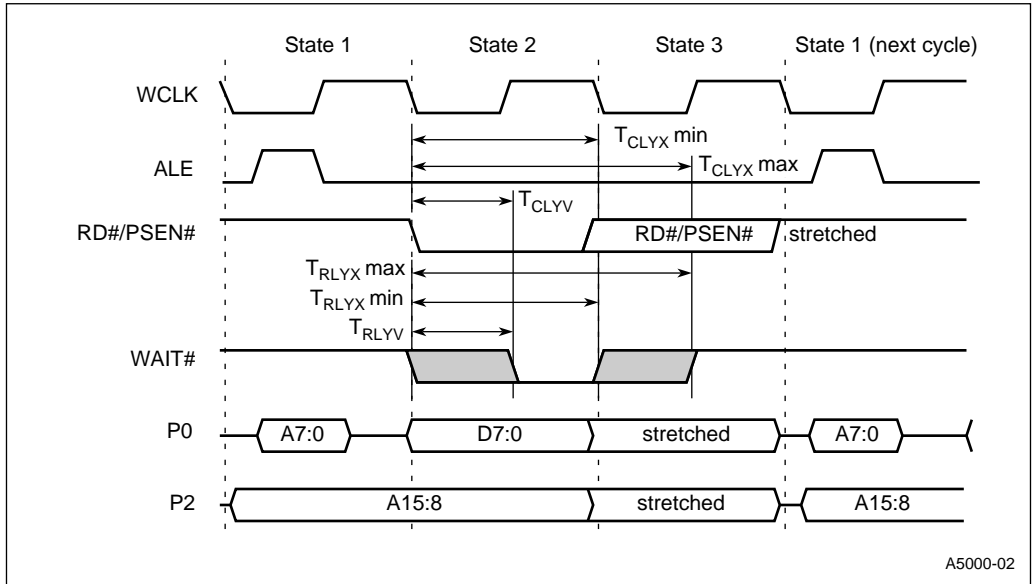


Figure 12. External Code Fetch/Data Read (Nonpage Mode, Real-time Wait State)

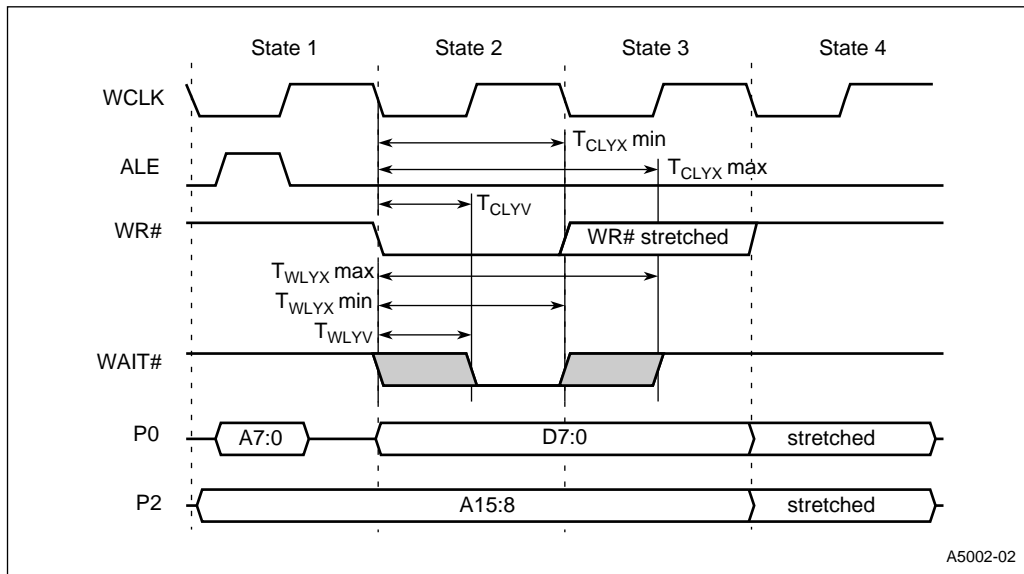


Figure 13. External Data Write (Nonpage Mode, Real-time Wait State)

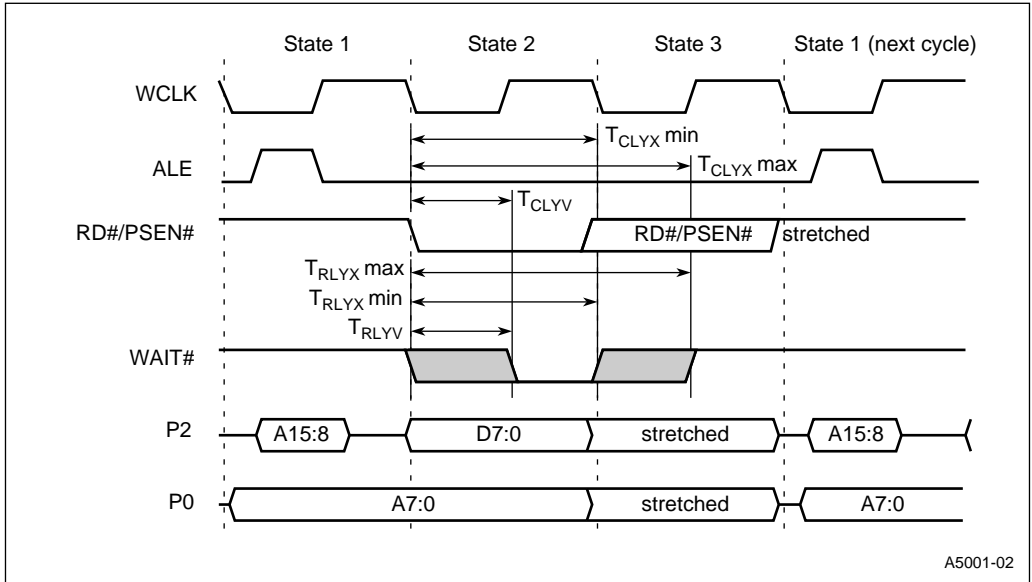


Figure 14. External Data Read (Page Mode, Real-time Wait State)

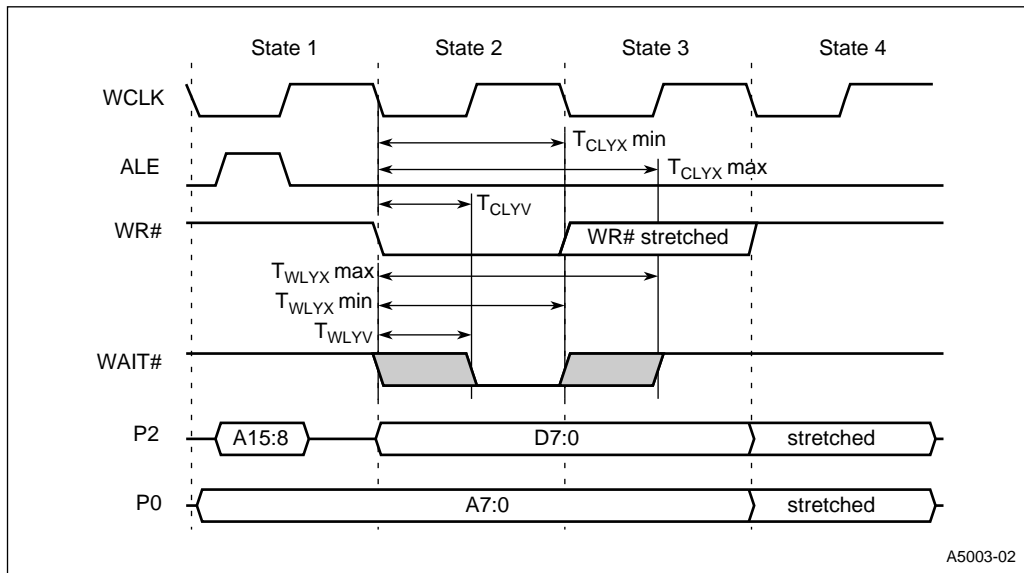


Figure 15. External Data Write (Page Mode, Real-time Wait State)

5.5 AC Characteristics — Serial Port, Synchronous Mode 0

Table 14. Serial Port Timing — Synchronous Mode 0

| Symbol | Parameter | Min | Max | Units |
|------------|--|-------------------|-------------------|-------|
| T_{XLXL} | Serial Port Clock Cycle Time | $6 T_{OSC}$ | | ns |
| T_{QVSH} | Output Data Setup to Clock Rising Edge | $5 T_{OSC} - 133$ | | ns |
| T_{SHQX} | Output Data hold after Clock Rising Edge | $T_{OSC} - 50$ | | ns |
| T_{XHDX} | Input Data Hold after Clock Rising Edge | 0 | | ns |
| T_{XHDV} | Clock Rising Edge to Input Data Valid | | $5 T_{OSC} - 133$ | ns |

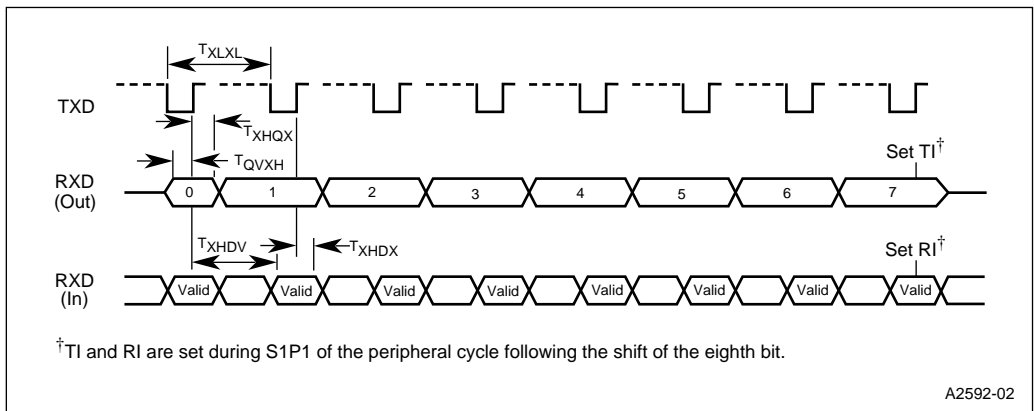


Figure 16. Serial Port Waveform — Synchronous Mode 0

5.6 External Clock Drive

Table 15. External Clock Drive

| Symbol | Parameter | Min | Max | Units |
|-------------|------------------------------------|----------------|----------------|-------|
| $1/T_{OSC}$ | Oscillator Frequency (F_{OSC}) | 6 | 12 | MHz |
| T_{CHCX} | High Time | $0.35 T_{OSC}$ | $0.65 T_{OSC}$ | ns |
| T_{CLCX} | Low Time | $0.35 T_{OSC}$ | $0.65 T_{OSC}$ | ns |
| T_{CLCH} | Rise Time | | 10 | ns |
| T_{CHCL} | Fall Time | | 10 | ns |

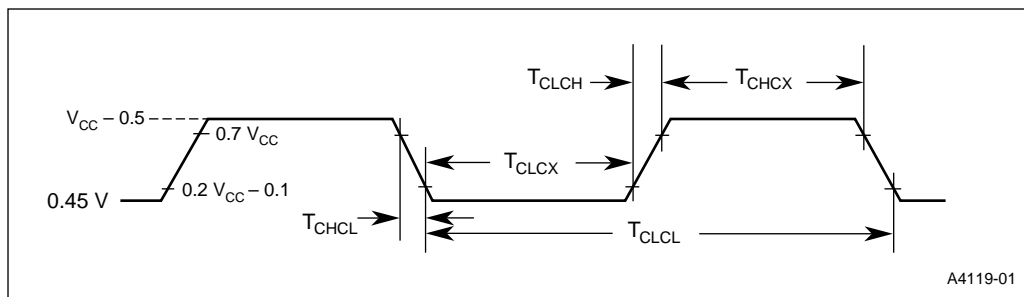


Figure 17. External Clock Drive Waveforms

5.7 Testing Waveforms

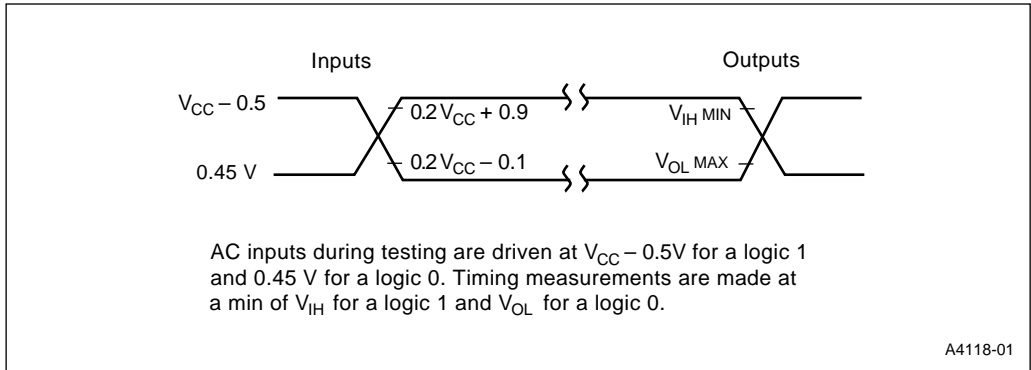


Figure 18. AC Testing Input, Output Waveforms

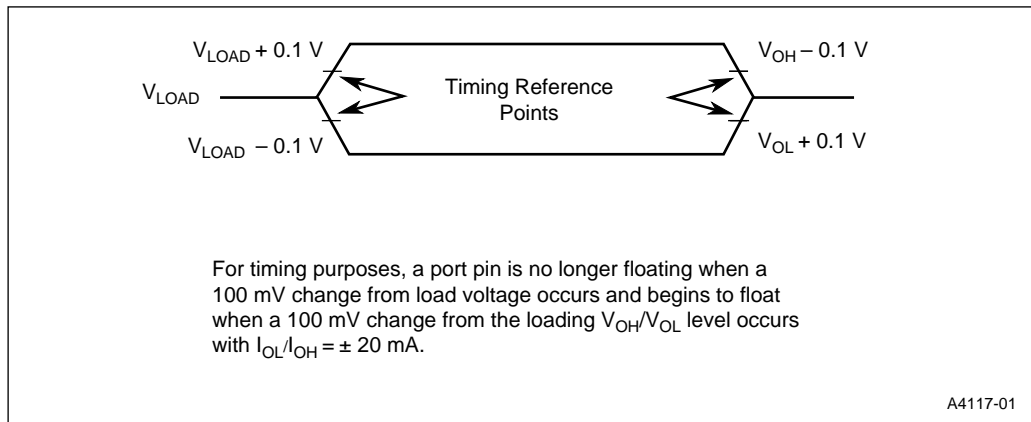


Figure 19. Float Waveforms

6.0 THERMAL CHARACTERISTICS

This microcontroller operates over the commercial temperature range from 0°C to 70°C. All thermal impedance data (Table 16) is approximate for static air conditions at 1 watt of power dissipation. Values change depending on operating conditions and application requirements. The Intel *Packaging Handbook* (order number 240800) describes Intel's thermal impedance test methodology. The *Components Quality and Reliability Handbook* (order number 210997) provides quality and reliability information.

Table 16. Thermal Characteristics

| Package Type | θ_{JA} | θ_{JC} |
|--------------|---------------|---------------|
| 68-pin PLCC | N/A | N/A |

7.0 PRODUCT REFERENCE

This section lists design considerations for the 8x930Ax Universal Serial Bus microcontroller.

7.1 External Bus Timing and Peripheral Timing Affected by PLLSEL2:0 Selection

PLLSEL2 (pin43), PLLSEL1 (pin 42), and PLLSELO (pin 44) determine the 8x930Ax internal CPU operating frequency. The selected CPU operating frequency also influences all the peripherals. If the PLLSEL2:0 pins of the 8x930Ax are set to 110, then the internal clock frequency is 12MHz, and one state time equals one clock time (please refer to Table 8 on page 12). Therefore, all internal and external instruction times for the timer, serial port, PCA, are two times faster than with other PLLSEL2:0 selections. Refer to the *8x930Ax, 8x930Hx Universal Serial Bus Microcontroller User's Manual* for the new peripheral timing formulas.

7.2 Low Clock Mode Frequency

In low clock mode, the CPU and peripherals run at 3 MHz. All external bus accesses are affected, including instruction fetch, data read/write, and peripheral timing. Please refer to Table 8 on page 12 for the relationship of 3 MHz CPU and peripheral timing (T_{CLK}) to state times. One peripheral cycle is 6 state times.

7.3 Setting FFRC Bit Clears Only the Oldest Packet in the FIFO

If the receive FIFO is set as a dual packet mode, it can receive two packets. Setting FFRC to indicate FIFO Read Complete will not flush the entire FIFO, only the oldest packet will be flushed. The read marker will be advanced to the location of the read pointer.

7.4 Series Resistor Requirement for Impedance Matching

Per the USB 1.0 specification (page 111, section 7.1.1.1), the impedance of the differential driver must be between 29 and 44 Ohms. To match the cable impedance, a series resistor of 27 to 33 Ohms should be connected to each USB line; i.e., on D_{P0} (pin 55) and on D_{M0} (pin 54). If the USB line is improperly terminated or not matched, signal fidelity will suffer. This can be seen on the scope as excessive overshoot and undershoot. This will potentially introduce bit errors.

7.5 Pullup Requirement for Full Speed Device and Low Speed Device

The pullup is a USB requirement to allow the host to identify which devices are low speed and which are full speed in order to communicate at the appropriate data rate. For Full Speed devices (12 Mbps) use a 1.5K pullup resistor (to 3.0 V – 3.6 V) on the D_{P0} line. For Low Speed devices (1.5Mbps), use a 1.5K pullup resistor (to 3.0 V – 3.6 V) on the D_{M0} line.

7.6 Powerdown Mode Cannot Be Invoked Before USB Suspend

If the 8x930Ax is put into powerdown mode prior to receiving a USB Suspend signal from the host, a USB Resume will not properly wake up the 8x930Ax from powerdown mode.

8.0 SPECIFICATION SUPPLEMENT FOR 8X930AX3 AND 8X930AX4

All descriptions above apply to the 8x930Ax and 8x930Ax2 microcontrollers. The following specifications apply to recent steppings of the 8x930Ax (8x930Ax3 and 8x930Ax4). This information is in addition to (or in place of) the specifications described above.

8.1 Six Endpoint Pairs Functionality

In the default state, the SIXEPEN bit of 8x930Ax3's and 8x930Ax4's EPCONFIG SFR is cleared and the 6 endpoint pair feature is disabled. In this state, the endpoint pairs of the 8x930Ax3 and 8x930Ax4 are similar to those of the 8x930Ax and 8x930Ax2 devices.

To enable the 6 endpoint pair feature, set EPCONFIG's SIXEPEN bit. The 8x930Ax3 and 8x930Ax4 will then have the endpoint pairs shown in Table 17.

Table 17. Six Endpoint Pair Feature

| EPINDEX | FFSZ1:0 | Transmit FIFO (bytes) | Receive FIFO (bytes) |
|-----------|---------|-----------------------|----------------------|
| 0xxx x000 | xx | 16 | 16 |
| 0xxx x001 | 00 | 256 | 256 |
| 0xxx x010 | xx | 32 | 32 |
| 0xxx x011 | xx | 32 | 32 |
| 0xxx x100 | xx | 32 | 32 |
| 0xxx x101 | xx | 16 | 16 |

When the 6 endpoint pair feature is enabled, two additional SFRs — the Function Interrupt Enable Register 1 (FIE1) and the Function Interrupt Flag Register 1 (FIFLG1) — are enabled to manage interrupts for the additional endpoint pairs.

See the *8x930Ax, 8x930Hx Universal Serial Bus Microcontroller User's Manual* for additional information.

8.2 DC Characteristics

The V_{OH} specification given in the DC Characteristics section of this datasheet is changed to $V_{OH} = \{min\} V_{CC} - 1.7 V$ when $I_{OH} = -60 \mu A$ for the A3 stepping onward.

8.3 Extended Data Float (EDF) AC Timing Feature

To provide a direct interface capability to slower memory without the use of tristate drivers, an extended data float (EDF) option has been added to the 8x930Ax3 and 8x930Ax4. This option is controlled by the EDF# bit (bit 3 in the UCONFIG1 configuration byte).

If the EDF# bit is configured to 1, the 8x930Ax3 and 8x930Ax4 behave per the current specification (some AC timings are different). This is known as "Compatibility Mode". Table 19 on page 32 lists the AC characteristics in this "Compatibility Mode" that are different compared to the 8x930Ax and 8x930Ax2. Parameters not listed in the table remain the same as for 8x930Ax and 8x930Ax2.

If the 8x930Ax3 and 8x930Ax4 are configured with EDF# = 0, the device will have extended data float timings. This mode is known as the "Increased T_{RHDZ1} Mode." Table 20 on page 32 and Table 21 on page 33 show the parameters that are affected when EDF# = 0.

Configuring the device with EDF# = 0 does not affect wait state A (all regions except 01:). Wait state A can have 0, 1, 2, or 3 wait states. EDF#=0 affects external wait state B (region 01:). The summary of the effect EDF# has on wait states is listed in Table 18.

Table 18. Effect of "EDF#" on Wait States

| EDF# | WSB#[1:0] | Wait-state (for page 01) |
|------|-----------|--------------------------|
| 1 | 11 | 0 |
| 1 | 10 | 1 |
| 1 | 01 | 2 |
| 1 | 00 | 3 |
| 0 | 11 | 1 |
| 0 | 10 | 1 |
| 0 | 01 | 3 |
| 0 | 00 | 3 |

Table 19. AC Characteristics for 8x930Ax3 and 8x930Ax4 in Compatibility Mode

| Symbol | Parameter | 8x930Ax3/8x930Ax4 Compatibility Mode (ns) (EDF# =1) (1) |
|--|--|---|
| T_{AVLL} | Address Valid to ALE Low | $(0.5+M)T_{CLK} - 13$ [min] |
| T_{LLAX} | Address Hold after ALE Low | 10 [min] |
| T_{WLWH} | WR# Pulse Width | $(1+N)T_{CLK} - 10$ [min] |
| T_{LLRL} | ALE Low to RD# or PSEN# low | 10 [min] |
| T_{LHAX} | ALE High to Address Hold | $(1+M)T_{CLK} - 27$ [min] |
| T_{RLDV} | RD# or PSEN# Low to Valid Data/Inst. In | $(1+N)T_{CLK} - 30$ [max] |
| T_{RLAZ} | RD# or PSEN# Low to Address Float | 3 max (2) |
| T_{RHDZ2} | Data Float After PSEN# or RD# High | $T_{CLK} + 10$ [max] |
| T_{RHLH2} | RD# or PSEN# High to ALE High (data) | $T_{CLK} + 10$ [min] |
| T_{WHLH} | WR# High to ALE High | $T_{CLK} + 10$ [min] |
| T_{AVDV2} | Address (demux'ed) Valid to Valid Data/Instr. In | $(2+M+N)T_{CLK} - 38$ [max] |
| T_{AVRL} | Address Valid to RD# or PSEN# Low | $(1+M)T_{CLK} - 40$ [min] |
| T_{AVWL1} | Address (mux'ed) Valid to WR# Low | $(1+M)T_{CLK} - 40$ [min] |
| NOTES: | | |
| 1. Device configured with default data float timing for fast memory interface. | | |
| 2. Typical value is 0 ns. | | |

Table 20. 8x930Ax3 and 8x930Ax4 Default and Extended Data Float Timings

| Sym- bol | Parameter | Default Data Float Timing (ns) Compatibility Mode (EDF# =1) (1,2,4,5) | Extended Data Float Timing (ns) Increased T_{RHDZ1} mode (EDF#=0) (1,3,4,5) |
|-------------|---|--|--|
| T_{LLAX} | Address Hold after ALE Low | 10 [min] | 20 [min] |
| T_{RLRH} | RD# or PSEN# Pulse Width | $(1+N)T_{CLK} - 10$ [min] | $(1+N)T_{CLK} - 32$ [min] |
| T_{WLWH} | WR# Pulse Width | $(1+N)T_{CLK} - 10$ [min] | $(1+N)T_{CLK} - 32$ [min] |
| T_{LLRL} | ALE Low to RD# or PSEN# low | 10 [min] | 20 [min] |
| T_{LHAX} | ALE High to Address Hold | $(1+M)T_{CLK} - 27$ [min] | $(0.5+M)T_{CLK} + 15$ [min] |
| T_{RLDV} | RD# or PSEN# Low to Valid Data/Inst. In | $(1+N)T_{CLK} - 30$ [max] | $(1+N)T_{CLK} - 50$ [max] |
| T_{RHDZ1} | Instruct. Float After PSEN# or RD# High | 10 [max] | $(0.5)T_{CLK} - 5$ [max] |

NOTES:

1. Worst-case numbers based on silicon data collected to date.
2. Device configured with default data float timing for fast memory interface.
3. Device configured with extended data float timing for slow memory interface.
4. The values listed are for 12 MHz. For 6 MHz, the value of T_{CLK} will double and will equal 166.6 ns.
5. M=0,1 is the extended ALE state; N= 0,1,2,3 is the RD#/PSEN#/WR# wait state.

Table 20. 8x930Ax3 and 8x930Ax4 Default and Extended Data Float Timings (Continued)

| Symbol | Parameter | Default Data Float Timing (ns) Compatibility Mode (EDF#=1) (1,2,4,5) | Extended Data Float Timing (ns) Increased T_{RHDZ1} mode (EDF#=0) (1,3,4,5) |
|-------------|---|--|---|
| T_{RHDZ2} | Data Float After PSEN# or RD# High | $T_{CLK} + 10$ [max] | $1.5 T_{CLK} - 5$ [max] |
| T_{RHLH2} | RD# or PSEN# High to ALE High (data) | $T_{CLK} + 10$ [min] | $(1.5)T_{CLK} - 7$ [min] |
| T_{RHLH1} | PSEN# High to ALE High (inst.) | 10 [min] | $(0.5)T_{CLK} - 7$ [min] |
| T_{WHLH} | WR# High to ALE High | $T_{CLK} + 10$ [min] | $(1.5)T_{CLK} - 7$ [min] |
| T_{AVDV1} | Address (mux'ed) Valid to Valid Data/Inst. In | $(2+M+N)T_{CLK} - 60$ [max] | $(1.5+M+N)T_{CLK} - 28$ [max] |
| T_{AVRL} | Address Valid to RD# or PSEN# Low | $(1+M)T_{CLK} - 40$ [min] | $(0.5+M)T_{CLK} + 10$ [min] |
| T_{AVWL1} | Address (mux'ed) Valid to WR# Low | $(1+M)T_{CLK} - 40$ [min] | $(0.5+M)T_{CLK} + 10$ [min] |
| T_{AVWL2} | Address (demux'ed) Valid to WR# Low | $(1+M)T_{CLK} - 17$ [min] | $(1+M)T_{CLK} + 10$ [min] |

NOTES:

1. Worst-case numbers based on silicon data collected to date.
2. Device configured with default data float timing for fast memory interface.
3. Device configured with extended data float timing for slow memory interface.
4. The values listed are for 12 MHz. For 6 MHz, the value of T_{CLK} will double and will equal 166.6 ns.
5. $M=0,1$ is the extended ALE state; $N=0,1,2,3$ is the RD#/PSEN#/WR# wait state.

Table 21. 8x930Ax3 and 8x930Ax4 Real-time Wait State AC Timing Specifications

| Symbol (Parameter) | F_{CLK} Variable Default Data Float Timing (ns) (EDF#=1) | | | F_{CLK} Variable Extended Data Float Timing (ns) (EDF#=0) | | |
|---|--|-----|--------------------|---|-----|--------------------|
| | Min | Typ | Max | Min | Typ | Max |
| T_{RLYV} (PSEN# or RD# Low to Wait Setup) | 0 | | $0.5 T_{CLK} - 13$ | 0 | | $0.5 T_{CLK} - 35$ |
| T_{WLYV} (WR# Low to Wait Setup) | 0 | | $0.5 T_{CLK} - 13$ | | | $0.5 T_{CLK} - 35$ |

9.0 DEVICE ERRATA

The 8x930Ax may contain design defects or errors known as errata. Characterized errata that may cause the 8x930Ax's behavior to deviate from published specifications are documented in a specification update. Refer to the *8x930Ax (8x930AD, 8x930AE) Specification Update* (Order Number 272940, Revision 007 or later). Specification updates can be obtained from your local Intel sales office or from the World Wide Web (www.intel.com).

10.0 DATASHEET REVISION HISTORY

This datasheet is valid for A-2 through A-4 step devices. Datasheets are changed as new device information becomes available. Verify with your local Intel sales office that you have the latest version before finalizing a design or ordering devices.

This (-003) revision of the 8x930Ax datasheet replaces earlier product information. The following changes were made in this version:

1. Added "Specification Supplement for 8x930Ax3 and 8x930Ax4" on page 31.
2. The following AC Characteristics were changed: T_{AVLL} , T_{AVDV1} , T_{AVRL} , T_{AVWL1} .
3. I_{CC} characteristics updated.